



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

For: **COMPUTER INTEGRATED MANUFACTURING TECHNIQUES**

[illegible]

Group Art Unit: 2121

Examiner:

Technology Center 2100

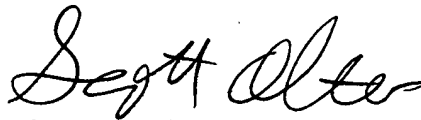
**Serial No. 10/084,092**

to present to the Office the relevant facts and law regarding the appropriate status of such document.

No certification or fee is believed to be required. However, the Commissioner is hereby authorized to charge any additional fees should any be required for this submission, or credit any overpayment to deposit account no. 08-0219.

Respectfully submitted,

HALE AND DORR LLP

A handwritten signature in black ink, appearing to read "Scott M. Alter", written in a cursive style.

Scott M. Alter

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Date: 4/25/03

**INFORMATION DISCLOSURE  
CITATION IN AN  
APPLICATION  
(PTO-1449)**



ATTY. DOCKET NO.  
004066 USA  
D01/Consilium/Consilium

SERIAL NO.  
10/084,092

APPLICANT  
John F. ARACKAPARAMBIL et al.

FILING DATE  
February 28, 2002

GROUP  
2121

**U.S. PATENT DOCUMENTS**

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	3,205,485	09/07/65	Noltingk			10/21/60
	3,229,198	01/11/66	Libby			09/28/62
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	4,302,721	11/24/81	Urbanek et al.			05/15/79
	4,750,141	06/07/88	Judell et al.			11/26/85
	4,757,259	07/12/88	Charpentier			11/05/86
	4,938,600	07/03/90	Into			02/09/89
	5,283,141	02/01/94	Yoon et al.			03/05/92
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	5,642,296	06/24/97	Saxena			07/29/93
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	5,735,055	04/07/98	Hochbein et al.			04/23/96
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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	6,159,075	12/12/00	Zhang			10/13/99
	6,159,644	12/12/00	Satoh et al.			03/06/96
	6,161,054	12/12/00	Rosenthal et al.			09/17/98
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	6,320,655	11/20/01	Matsushita et al.			03/15/00

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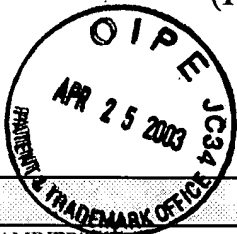
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	2001/0042690	11/22/01	Talieh			12/14/00
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	2002/0032499	03/14/02	Wilson et al.			05/04/01
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	2002/0058460	05/16/02	Lee et al.			09/14/01
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	6,455,937	09/24/02	Cunningham			03/17/99
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	2002/0185658	12/12/02	Inoue et al.			06/14/01
	2002/0193902	12/19/02	Shanmugasundram et al.			06/18/02
	2002/0197745	12/26/02	Shanmugasundram et al.			08/31/01
	2002/0197934	12/26/02	Paik			11/30/01
	2002/0199082	12/26/02	Shanmugasundram et al.			06/18/02
	6,503,839	01/07/03	Gonzales et al.			07/03/01
	2003/0020909	01/30/03	Adams et al.			04/09/01
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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
	61-66104	04/04/86	Japan			X	
	3-202710	09/04/91	Japan			X	
	8-23166	01/23/96	Japan			X	
	9-246547	09/19/97	Japan			X	
	WO 98/05066	02/05/98	WIPO			X	
	10-34522	02/10/98	Japan			X	
	0 869 652	10/07/98	Europe			X	
	WO 99/09371	02/25/99	WIPO			X	
	0 910 123	04/21/99	Europe			X	
	0 932 194	07/28/99	Europe			X	
	WO 00/00874	01/06/00	WIPO			X	
	2000-183001	06/30/00	Japan			X	

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<b>FOREIGN PATENT DOCUMENTS</b>							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
	1 071 128	01/24/01	Europe			X	
	WO 01/18623	03/15/01	WIPO			X	
	WO 01/25865	04/12/01	WIPO			X	
	434103	05/16/01	Taiwan			X	
	436383	05/28/01	Taiwan			X	
	455938	09/21/01	Taiwan			X	
	455976	09/21/01	Taiwan			X	
	2001-284299	10/12/01	Japan			X	
	2001-305108	10/31/01	Japan			X	
	2002-9030	01/11/02	Japan			X	
	WO 02/074491	09/26/02	WIPO			X	
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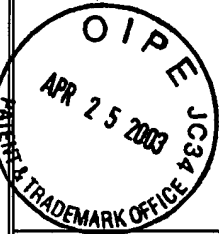


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<p style="text-align: center;"><b>OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)</b></p>		
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<p><b>OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)</b></p>		
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